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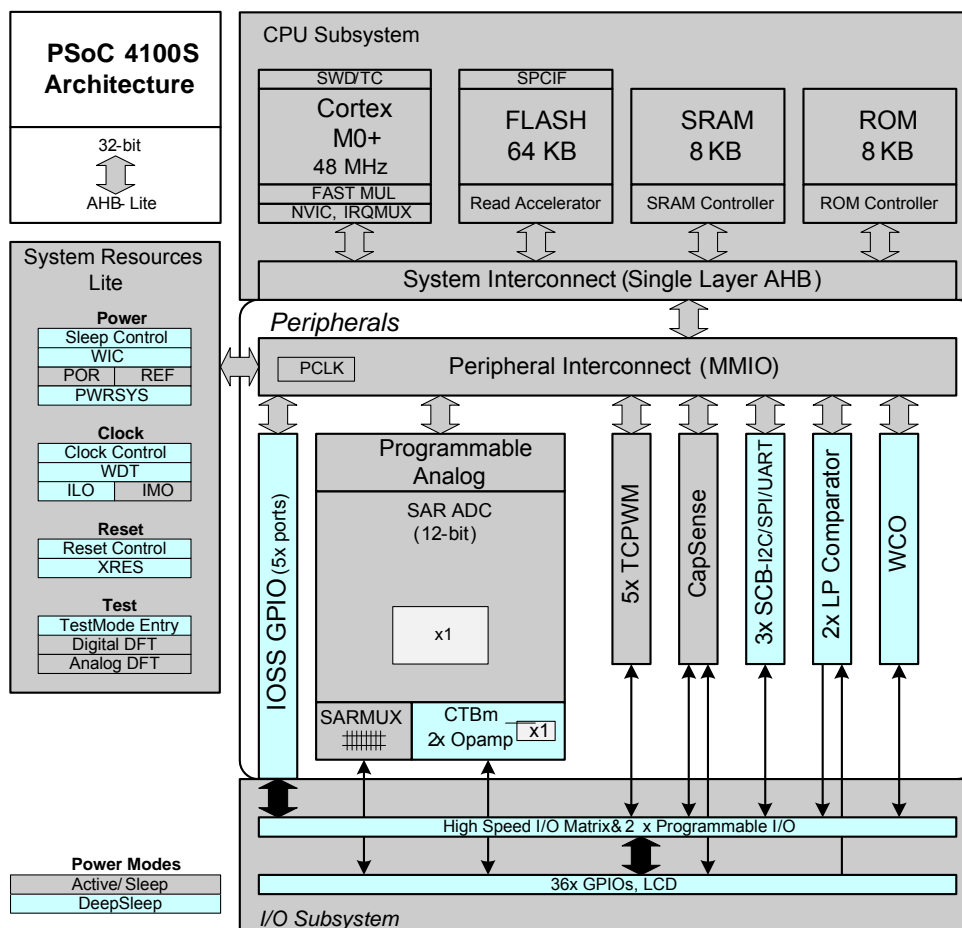
"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I ² C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x10b Slope, 16x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4125axi-s433

Figure 1. Block Diagram



PSoC 4100S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4100S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4100S family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4100S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4100S allows the customer to make.

Reset

The PSoC 4100S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

Analog Blocks

12-bit SAR ADC

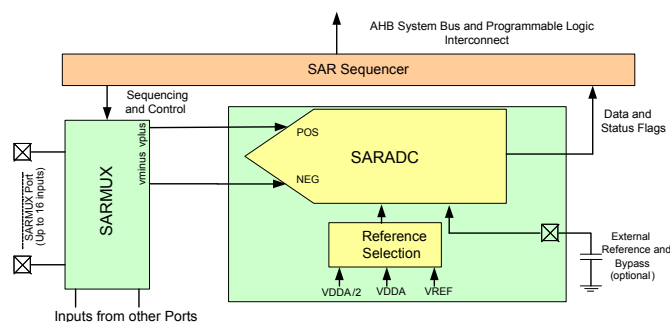
The 12-bit, 1-Msps SAR ADC can operate at a maximum clock rate of 18 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The Sample-and-Hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. It is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) with zero switching overhead (that is, aggregate sampling bandwidth is equal to 1 Msps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is not available in Deep Sleep mode as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

Figure 3. SAR ADC



Two Opamps (Continuous-Time Block; CTB)

The PSoC 4100S has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, Voltage

Buffers, Filters, Trans-Impedance Amplifiers, and other functions can be realized, in some cases with external passives, saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering.

Low-power Comparators (LPC)

The PSoC 4100S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

Current DACs

The PSoC 4100S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

Analog Multiplexed Buses

The PSoC 4100S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

Programmable Digital Blocks

The Programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

Fixed Function Digital

Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4100S.

Serial Communication Block (SCB)

The PSoC 4100S has three serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

I²C Mode: The hardware I²C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also

supports EZI2C that creates a mailbox address range in the memory of the PSoC 4100S and effectively reduces I²C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I²C peripheral is compatible with the I²C Standard-mode and Fast-mode devices as defined in the NXP I²C-bus specification and user manual (UM10204). The I²C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4100S is not completely compliant with the I²C spec in the following respect:

- GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I²C system.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

GPIO

The PSoC 4100S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
 - Analog input mode (input and output buffers disabled)
 - Input only
 - Weak pull-up with strong pull-down
 - Strong pull-up with weak pull-down
 - Open drain with strong pull-down
 - Open drain with strong pull-up
 - Strong pull-up with strong pull-down
 - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4100S).

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4100S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and ground to null out power-supply related noise.

LCD Segment Drive

The PSoC 4100S has an LCD controller, which can drive up to 4 commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).

Pinouts

The following table provides the pin list for PSoC 4100S for the 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball CSP packages. All port pins support GPIO.

Table 1. Pin List

48-TQFP		44-TQFP		40-QFN		32-QFN		35-CSP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
28	P0.0	24	P0.0	22	P0.0	17	P0.0	C3	P0.0
29	P0.1	25	P0.1	23	P0.1	18	P0.1	A5	P0.1
30	P0.2	26	P0.2	24	P0.2	19	P0.2	A4	P0.2
31	P0.3	27	P0.3	25	P0.3	20	P0.3	A3	P0.3
32	P0.4	28	P0.4	26	P0.4	21	P0.4	B3	P0.4
33	P0.5	29	P0.5	27	P0.5	22	P0.5	A6	P0.5
34	P0.6	30	P0.6	28	P0.6	23	P0.6	B4	P0.6
35	P0.7	31	P0.7	29	P0.7			B5	P0.7
36	XRES	32	XRES	30	XRES	24	XRES	B6	XRES
37	VCCD	33	VCCD	31	VCCD	25	VCCD	A7	VCCD
38	VSSD			DN	VSSD	26	VSSD	B7	VSS
39	VDDD	34	VDDD	32	VDDD			C7	VDD
40	VDDA	35	VDDA	33	VDDA	27	VDD	C7	VDD
41	VSSA	36	VSSA	34	VSSA	28	VSSA	B7	VSS
42	P1.0	37	P1.0	35	P1.0	29	P1.0	C4	P1.0
43	P1.1	38	P1.1	36	P1.1	30	P1.1	C5	P1.1
44	P1.2	39	P1.2	37	P1.2	31	P1.2	C6	P1.2
45	P1.3	40	P1.3	38	P1.3	32	P1.3	D7	P1.3
46	P1.4	41	P1.4	39	P1.4			D4	P1.4
47	P1.5	42	P1.5					D5	P1.5
48	P1.6	43	P1.6					D6	P1.6
1	P1.7/VREF	44	P1.7/VREF	40	P1.7/VREF	1	P1.7/VREF	E7	P1.7/VREF
		1	VSSD						
2	P2.0	2	P2.0	1	P2.0	2	P2.0		
3	P2.1	3	P2.1	2	P2.1	3	P2.1		
4	P2.2	4	P2.2	3	P2.2	4	P2.2	D3	P2.2
5	P2.3	5	P2.3	4	P2.3	5	P2.3	E4	P2.3
6	P2.4	6	P2.4	5	P2.4			E5	P2.4
7	P2.5	7	P2.5	6	P2.5	6	P2.5	E6	P2.5
8	P2.6	8	P2.6	7	P2.6	7	P2.6	E3	P2.6
9	P2.7	9	P2.7	8	P2.7	8	P2.7	E2	P2.7
10	VSSD	10	VSSD	9	VSSD				
12	P3.0	11	P3.0	10	P3.0	9	P3.0	E1	P3.0
13	P3.1	12	P3.1	11	P3.1	10	P3.1	D2	P3.1
14	P3.2	13	P3.2	12	P3.2	11	P3.2	D1	P3.2
16	P3.3	14	P3.3	13	P3.3	12	P3.3	C1	P3.3
17	P3.4	15	P3.4	14	P3.4			C2	P3.4
18	P3.5	16	P3.5	15	P3.5				

Alternate Pin Functions

Each Port pin has can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]	scb[2].i2c_scl:0	scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]	scb[2].i2c_sda:0	scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						scb[2].spi_select0
P0.4	wco.wco_in			scb[1].uart_rx:0	scb[2].uart_rx:0	scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0	scb[2].uart_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0	scb[2].uart_tx:1		scb[1].spi_clk:1
P0.7			tcpwm.line[0]:2	scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0	ctb0_oa0+		tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0_oa0-		tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0_oa0_out		tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]	scb[2].i2c_scl:1	scb[0].spi_clk:1
P1.3	ctb0_oa1_out		tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]	scb[2].i2c_sda:1	scb[0].spi_select0:1
P1.4	ctb0_oa1-						scb[0].spi_select1:1
P1.5	ctb0_oa1+						scb[0].spi_select2:1
P1.6	ctb0_oa0+						scb[0].spi_select3:1
P1.7	ctb0_oa1+ sar_ext_vref0 sar_ext_vref1						scb[2].spi_clk
P2.0	sarmux[0]	prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux[1]	prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux[2]	prgio[0].io[2]					scb[1].spi_clk:2
P2.3	sarmux[3]	prgio[0].io[3]					scb[1].spi_select0:2

Electrical Specifications

Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings^[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID1	V _{DDD_ABS}	Digital supply relative to V _{SS}	−0.5	—	6	V	—
SID2	V _{CCD_ABS}	Direct digital core voltage input relative to V _{SS}	−0.5	—	1.95		—
SID3	V _{GPIO_ABS}	GPIO voltage	−0.5	—	V _{DD} +0.5		—
SID4	I _{GPIO_ABS}	Maximum current per GPIO	−25	—	25	mA	—
SID5	I _{GPIO_injection}	GPIO injection current, Max for V _{IH} > V _{DDD} , and Min for V _{IL} < V _{SS}	−0.5	—	0.5		Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	—	—	V	—
BID45	ESD_CDM	Electrostatic discharge charged device model	500	—	—		—
BID46	LU	Pin current for latch-up	−140	—	140	mA	—

Device Level Specifications

All specifications are valid for −40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 3. DC Specifications

Typical values measured at V_{DD} = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID53	V _{DD}	Power supply input voltage	1.8	—	5.5	V	Internally regulated supply
SID255	V _{DD}	Power supply input voltage (V _{CCD} = V _{DDD} = V _{DDA})	1.71	—	1.89		Internally unregulated supply
SID54	V _{CCD}	Output voltage (for core logic)	—	1.8	—		—
SID55	C _{EFC}	External regulator voltage bypass	—	0.1	—	μF	X5R ceramic or better
SID56	C _{EXC}	Power supply bypass capacitor	—	1	—		X5R ceramic or better

Active Mode, V_{DD} = 1.8 V to 5.5 V. Typical values measured at V_{DD} = 3.3 V and 25 °C.

SID10	I _{DD5}	Execute from flash; CPU at 6 MHz	—	1.8	2.7	mA	Max is at 85 °C and 5.5 V
SID16	I _{DD8}	Execute from flash; CPU at 24 MHz	—	3.0	4.75		Max is at 85 °C and 5.5 V
SID19	I _{DD11}	Execute from flash; CPU at 48 MHz	—	5.4	6.85		Max is at 85 °C and 5.5 V

Note

- Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.

GPIO

Table 5. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	$V_{IH}^{[3]}$	Input voltage high threshold	$0.7 \times V_{DDD}$	–	–	V	CMOS Input
SID58	V_{IL}	Input voltage low threshold	–	–	$0.3 \times V_{DDD}$		CMOS Input
SID241	$V_{IH}^{[3]}$	LVTTL input, $V_{DDD} < 2.7$ V	$0.7 \times V_{DDD}$	–	–		–
SID242	V_{IL}	LVTTL input, $V_{DDD} < 2.7$ V	–	–	$0.3 \times V_{DDD}$		–
SID243	$V_{IH}^{[3]}$	LVTTL input, $V_{DDD} \geq 2.7$ V	2.0	–	–		–
SID244	V_{IL}	LVTTL input, $V_{DDD} \geq 2.7$ V	–	–	0.8		–
SID59	V_{OH}	Output voltage high level	$V_{DDD} - 0.6$	–	–		$I_{OH} = 4$ mA at 3 V V_{DDD}
SID60	V_{OH}	Output voltage high level	$V_{DDD} - 0.5$	–	–		$I_{OH} = 1$ mA at 1.8 V V_{DDD}
SID61	V_{OL}	Output voltage low level	–	–	0.6		$I_{OL} = 4$ mA at 1.8 V V_{DDD}
SID62	V_{OL}	Output voltage low level	–	–	0.6		$I_{OL} = 10$ mA at 3 V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4		$I_{OL} = 3$ mA at 3 V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	k Ω	–
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5		–
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, $V_{DDD} = 3.0$ V
SID66	C_{IN}	Input capacitance	–	–	7	pF	–
SID67 ^[4]	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq 2.7$ V
SID68 ^[4]	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DDD}$	–	–		$V_{DD} < 4.5$ V
SID68A ^[4]	$V_{HYSCMOS5V5}$	Input hysteresis CMOS	200	–	–		$V_{DD} > 4.5$ V
SID69 ^[4]	I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	μ A	–
SID69A ^[4]	I_{TOT_GPIO}	Maximum total source or sink chip current	–	–	200	mA	–

Table 6. GPIO AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3 V V_{DDD} , Load = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12		3.3 V V_{DDD} , Load = 25 pF
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60	–	3.3 V V_{DDD} , Load = 25 pF

Notes

3. V_{IH} must not exceed $V_{DDD} + 0.2$ V.
4. Guaranteed by characterization.

Table 6. GPIO AC Specifications

(Guaranteed by Characterization) (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID73	T_{FALLS}	Fall time in slow strong mode	10	–	60	–	3.3 V V_{DD} , Load = 25 pF
SID74	$F_{GPIOOUT1}$	GPIO F_{OUT} ; 3.3 V $\leq V_{DD} \leq 5.5$ V Fast strong mode	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOOUT2}$	GPIO F_{OUT} ; 1.71 V $\leq V_{DD} \leq 3.3$ V Fast strong mode	–	–	16.7		90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOOUT3}$	GPIO F_{OUT} ; 3.3 V $\leq V_{DD} \leq 5.5$ V Slow strong mode	–	–	7		90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOOUT4}$	GPIO F_{OUT} ; 1.71 V $\leq V_{DD} \leq 3.3$ V Slow strong mode.	–	–	3.5		90/10%, 25 pF load, 60/40 duty cycle
SID246	F_{GPIOIN}	GPIO input operating frequency; 1.71 V $\leq V_{DD} \leq 5.5$ V	–	–	48		90/10% V_{IO}

XRES

Table 7. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	V_{IH}	Input voltage high threshold	$0.7 \times V_{DD}$	–	–	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	–	–	$0.3 \times V_{DD}$		
SID79	R_{PULLUP}	Pull-up resistor	–	60	–	k Ω	–
SID80	C_{IN}	Input capacitance	–	–	7	pF	–
SID81 ^[5]	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Typical hysteresis is 200 mV for $V_{DD} > 4.5$ V
SID82	I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	μ A	

Table 8. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83 ^[5]	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	μ s	–
BID194 ^[5]	$T_{RESETWAKE}$	Wake-up time from reset release	–	–	2.7	ms	–

Note

5. Guaranteed by characterization.

Analog Peripherals

Table 9. CTBm Opamp Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
	I _{DD}	Opamp block current, External load					
SID269	I _{DD_HI}	power=hi	–	1100	1850	μA	–
SID270	I _{DD_MED}	power=med	–	550	950		–
SID271	I _{DD_LOW}	power=lo	–	150	350		–
	G _{BW}	Load = 20 pF, 0.1 mA V _{D_{DDA}} = 2.7 V					
SID272	G _{BW_HI}	power=hi	6	–	–	MHz	Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
SID273	G _{BW_MED}	power=med	3	–	–		Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
SID274	G _{BW_LO}	power=lo	–	1	–		Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
	I _{OUT_MAX}	V _{D_{DDA}} = 2.7 V, 500 mV from rail					
SID275	I _{OUT_MAX_HI}	power=hi	10	–	–	mA	Output is 0.5 V V _{D_{DDA}} -0.5 V
SID276	I _{OUT_MAX_MID}	power=mid	10	–	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
SID277	I _{OUT_MAX_LO}	power=lo	–	5	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
	I _{OUT}	V _{D_{DDA}} = 1.71 V, 500 mV from rail					
SID278	I _{OUT_MAX_HI}	power=hi	4	–	–	mA	Output is 0.5 V V _{D_{DDA}} -0.5 V
SID279	I _{OUT_MAX_MID}	power=mid	4	–	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
SID280	I _{OUT_MAX_LO}	power=lo	–	2	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
	I _{DD_Int}	Opamp block current Internal Load					
SID269_I	I _{DD_HI_Int}	power=hi	–	1500	1700	μA	–
SID270_I	I _{DD_MED_Int}	power=med	–	700	900		–
SID271_I	I _{DD_LOW_Int}	power=lo	–	–	–		–
	G _{BW}	V _{D_{DDA}} = 2.7 V	–	–	–		–
SID272_I	G _{BW_HI_Int}	power=hi	8	–	–	MHz	Output is 0.25 V to V _{D_{DDA}} -0.25 V

Table 9. CTBm Opamp Specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID299	T_OP_WAKE	From disable to enable, no external RC dominating	–	–	25	μs	–
SID299A	OL_GAIN	Open Loop Gain	–	90	–	dB	
	COMP_MODE	Comparator mode; 50 mV drive, $T_{rise}=T_{fall}$ (approx.)					
SID300	TPD1	Response time; power=hi	–	150	–	ns	Input is 0.2 V to $V_{DDA}-0.2$ V
SID301	TPD2	Response time; power=med	–	500	–		Input is 0.2 V to $V_{DDA}-0.2$ V
SID302	TPD3	Response time; power=lo	–	2500	–		Input is 0.2 V to $V_{DDA}-0.2$ V
SID303	VHYST_OP	Hysteresis	–	10	–	mV	–
SID304	WUP_CTB	Wake-up time from Enabled to Usable	–	–	25	μs	–
	Deep Sleep Mode	Mode 2 is lowest current range. Mode 1 has higher GBW.					
SID_DS_1	I _{DD_HI_M1}	Mode 1, High current	–	1400	–	μA	25 °C
SID_DS_2	I _{DD_MED_M1}	Mode 1, Medium current	–	700	–		25 °C
SID_DS_3	I _{DD_LOW_M1}	Mode 1, Low current	–	200	–		25 °C
SID_DS_4	I _{DD_HI_M2}	Mode 2, High current	–	120	–		25 °C
SID_DS_5	I _{DD_MED_M2}	Mode 2, Medium current	–	60	–		25 °C
SID_DS_6	I _{DD_LOW_M2}	Mode 2, Low current	–	15	–		25 °C

Table 9. CTBm Opamp Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID_DS_7	G _{BW_HI_M1}	Mode 1, High current	–	4	–	MHz	20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_8	G _{BW_MED_M1}	Mode 1, Medium current	–	2	–		20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_9	G _{BW_LOW_M1}	Mode 1, Low current	–	0.5	–		20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_10	G _{BW_HI_M2}	Mode 2, High current	–	0.5	–		20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_11	G _{BW_MED_M2}	Mode 2, Medium current	–	0.2	–		20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_12	G _{BW_LOW_M2}	Mode 2, Low current	–	0.1	–		20-pF load, no DC load 0.2 V to V _{DDA} -0.2 V
SID_DS_13	V _{OS_HI_M1}	Mode 1, High current	–	5	–	mV	With trim 25 °C, 0.2 V to V _{DDA} -0.2 V
SID_DS_14	V _{OS_MED_M1}	Mode 1, Medium current	–	5	–		With trim 25 °C, 0.2 V to V _{DDA} -0.2 V
SID_DS_15	V _{OS_LOW_M2}	Mode 1, Low current	–	5	–		With trim 25 °C, 0.2 V to V _{DDA} -0.2 V
SID_DS_16	V _{OS_HI_M2}	Mode 2, High current	–	5	–		With trim 25 °C, 0.2V to V _{DDA} -0.2 V
SID_DS_17	V _{OS_MED_M2}	Mode 2, Medium current	–	5	–		With trim 25 °C, 0.2 V to V _{DDA} -0.2 V
SID_DS_18	V _{OS_LOW_M2}	Mode 2, Low current	–	5	–		With trim 25 °C, 0.2 V to V _{DDA} -0.2 V
SID_DS_19	I _{OUT_HI_M1}	Mode 1, High current	–	10	–	mA	Output is 0.5 V to V _{DDA} -0.5 V
SID_DS_20	I _{OUT_MED_M1}	Mode 1, Medium current	–	10	–		Output is 0.5 V to V _{DDA} -0.5 V
SID_DS_21	I _{OUT_LOW_M1}	Mode 1, Low current	–	4	–		Output is 0.5 V to V _{DDA} -0.5 V
SID_DS_22	I _{OUT_HI_M2}	Mode 2, High current	–	1	–		
SID_DS_23	I _{OU_MED_M2}	Mode 2, Medium current	–	1	–		
SID_DS_24	I _{OU_LOW_M2}	Mode 2, Low current	–	0.5	–		

Note

6. Guaranteed by characterization.

Table 13. SAR Specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID99	A_OFFSET	Input offset voltage	–	–	2	mV	Measured with 1-V reference
SID100	A_ISAR	Current consumption	–	–	1	mA	
SID101	A_VINS	Input voltage range - single ended	V _{SS}	–	V _{DDA}	V	
SID102	A_VIND	Input voltage range - differential[V _{SS}	–	V _{DDA}	V	
SID103	A_INRES	Input resistance	–	–	2.2	KΩ	
SID104	A_INCAP	Input capacitance	–	–	10	pF	
SID260	VREFSAR	Trimmed internal reference to SAR	–	–	TBD	V	
SAR ADC AC Specifications							
SID106	A_PSRR	Power supply rejection ratio	70	–	–	dB	
SID107	A_CMRR	Common mode rejection ratio	66	–	–	dB	Measured at 1 V
SID108	A_SAMP	Sample rate	–	–	1	Msps	
SID109	A_SNR	Signal-to-noise and distortion ratio (SINAD)	65	–	–	dB	F _{IN} = 10 kHz
SID110	A_BW	Input bandwidth without aliasing	–	–	A _{samp} /2	kHz	
SID111	A_INL	Integral non linearity. V _{DD} = 1.71 to 5.5, 1 Msps	–1.7	–	2	LSB	V _{REF} = 1 to V _{DD}
SID111A	A_INL	Integral non linearity. V _{DD} = 1.71 to 3.6, 1 Msps	–1.5	–	1.7	LSB	V _{REF} = 1.71 to V _{DD}
SID111B	A_INL	Integral non linearity. V _{DD} = 1.71 to 5.5, 500 ksps	–1.5	–	1.7	LSB	V _{REF} = 1 to V _{DD}
SID112	A_DNL	Differential non linearity. V _{DD} = 1.71 to 5.5, 1 Msps	–1	–	2.2	LSB	V _{REF} = 1 to V _{DD}
SID112A	A_DNL	Differential non linearity. V _{DD} = 1.71 to 3.6, 1 Msps	–1	–	2	LSB	V _{REF} = 1.71 to V _{DD}
SID112B	A_DNL	Differential non linearity. V _{DD} = 1.71 to 5.5, 500 ksps	–1	–	2.2	LSB	V _{REF} = 1 to V _{DD}
SID113	A_THD	Total harmonic distortion	–	–	–65	dB	F _{in} = 10 kHz
SID261	FSARINTRE F	SAR operating speed without external ref. bypass	–	–	100	ksps	12-bit resolution

CSD

Table 14. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	–	–	±50	mV	$V_{DD} > 2\text{ V}$ (with ripple), 25°C T_A , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	–	–	±25	mV	$V_{DD} > 1.75\text{V}$ (with ripple), 25°C T_A , Parasitic Capacitance (C_P) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	–	–	4000	μA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V _{REF}	Voltage reference for CSD and Comparator	0.6	1.2	$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	–	–	1750	μA	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	–	–	1750	μA	
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	–	$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	–1	–	1	LSB	
SID310	IDAC1INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for $V_{DDA} < 2\text{ V}$
SID311	IDAC2DNL	DNL	–1	–	1	LSB	
SID312	IDAC2INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for $V_{DDA} < 2\text{ V}$
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. $V_{DDA} > 2\text{ V}$.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	–	5.4	μA	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1 (7 bits) in medium range	34	–	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1 (7 bits) in high range	275	–	330	μA	LSB = 2.4-μA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	–	10.5	μA	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1 (7 bits) in medium range, 2X mode	69	–	82	μA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1 (7 bits) in high range, 2X mode	540	–	660	μA	LSB = 4.8-μA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	–	5.4	μA	LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	–	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	–	330	μA	LSB = 2.4-μA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	–	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2 (7 bits) in medium range, 2X mode	69	–	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2 (7 bits) in high range, 2X mode	540	–	660	μA	LSB = 4.8-μA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	–	10.5	μA	LSB = 37.5-nA typ.

Table 14. CSD and IDAC Specifications (continued)

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	–	82	µA	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	–	660	µA	LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	–	–	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	–	–	±10	%	
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	–	–	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	–	–	5.6	LSB	LSB = 300-nA typ.
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	–	–	6.8	LSB	LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	–	2.2	–	nF	5-V rating, X7R or NP0 cap.

Table 15. 10-bit CapSense ADC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SIDA94	A_RES	Resolution	–	–	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	–	–	16		Defined by AMUX Bus.
SIDA97	A-MONO	Monotonicity	–	–	–	Yes	
SIDA98	A_GAINERR	Gain error	–	–	±2	%	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA99	A_OFFSET	Input offset voltage	–	–	3	mV	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA100	A_ISAR	Current consumption	–	–	0.25	mA	
SIDA101	A_VINS	Input voltage range - single ended	V _{SSA}	–	V _{DDA}	V	
SIDA103	A_INRES	Input resistance	–	2.2	–	KΩ	
SIDA104	A_INCAP	Input capacitance	–	20	–	pF	
SIDA106	A_PSRR	Power supply rejection ratio	–	60	–	dB	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA107	A_TACQ	Sample acquisition time	–	1	–	µs	
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = F _{clk} /(2 ^{N+2}). Clock frequency = 48 MHz.	–	–	21.3	µs	Does not include acquisition time. Equivalent to 44.8 ksp/s including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = F _{clk} /(2 ^{N+2}). Clock frequency = 48 MHz.	–	–	85.3	µs	Does not include acquisition time. Equivalent to 11.6 ksp/s including acquisition time.

Table 21. UART DC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I _{UART1}	Block current consumption at 100 Kbps	–	–	55	μA	–
SID161	I _{UART2}	Block current consumption at 1000 Kbps	–	–	312	μA	–

Table 22. UART AC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F _{UART}	Bit rate	–	–	1	Mbps	–

Table 23. LCD Direct Drive DC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I _{LCDLOW}	Operating current in low power mode	–	5	–	μA	16 × 4 small segment disp. at 50 Hz
SID155	C _{LDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID156	LCD _{OFFSET}	Long-term segment offset	–	20	–	mV	–
SID157	I _{LCDOP1}	LCD system operating current V _{bias} = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I _{LCDOP2}	LCD system operating current V _{bias} = 3.3 V	–	2	–		32 × 4 segments. 50 Hz. 25 °C

Table 24. LCD Direct Drive AC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F _{LCD}	LCD frame rate	10	50	150	Hz	–

Note

9. Guaranteed by characterization.

Memory

Table 25. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V _{PE}	Erase and program voltage	1.71	–	5.5	V	–

Table 26. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	T _{ROWWRITE} ^[10]	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID175	T _{ROWERASE} ^[10]	Row erase time	–	–	16		–
SID176	T _{ROWPROGRAM} ^[10]	Row program time after erase	–	–	4		–
SID178	T _{BULKERASE} ^[10]	Bulk erase time (64 KB)	–	–	35		–
SID180 ^[11]	T _{DEVPROG} ^[10]	Total device program time	–	–	7	Seconds	–
SID181 ^[11]	F _{END}	Flash endurance	100 K	–	–	Cycles	–
SID182 ^[11]	F _{RET}	Flash retention. T _A ≤ 55 °C, 100 K P/E cycles	20	–	–	Years	–
SID182A ^[11]	–	Flash retention. T _A ≤ 85 °C, 10 K P/E cycles	10	–	–		–
SID256	TWS48	Number of Wait states at 48 MHz	2	–	–		CPU execution from Flash
SID257	TWS24	Number of Wait states at 24 MHz	1	–	–		CPU execution from Flash

System Resources

Power-on Reset (POR)

Table 27. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	–	67	V/ms	At power-up
SID185 ^[11]	V _{RISEIPOR}	Rising trip voltage	0.80	–	1.5	V	–
SID186 ^[11]	V _{FALLIPOR}	Falling trip voltage	0.70	–	1.4		–

Table 28. Brown-out Detect (BOD) for V_{CCD}

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190 ^[11]	V _{FALLPPOR}	BOD trip voltage in active and sleep modes	1.48	–	1.62	V	–
SID192 ^[11]	V _{FALLDPSLP}	BOD trip voltage in Deep Sleep	1.11	–	1.5		–

Notes

10. It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

11. Guaranteed by characterization.

SWD Interface

Table 29. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCCLK1	$3.3\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	–	–	14	MHz	SWDCCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCCLK2	$1.71\text{ V} \leq V_{DD} \leq 3.3\text{ V}$	–	–	7		SWDCCLK ≤ 1/3 CPU clock frequency
SID215 ^[12]	T_SWDI_SETUP	$T = 1/f_{\text{SWDCCLK}}$	$0.25 \cdot T$	–	–	ns	–
SID216 ^[12]	T_SWDI_HOLD	$T = 1/f_{\text{SWDCCLK}}$	$0.25 \cdot T$	–	–		–
SID217 ^[12]	T_SWDO_VALID	$T = 1/f_{\text{SWDCCLK}}$	–	–	$0.5 \cdot T$		–
SID217A ^[12]	T_SWDO_HOLD	$T = 1/f_{\text{SWDCCLK}}$	1	–	–		–

Internal Main Oscillator

Table 30. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I _{IMO1}	IMO operating current at 48 MHz	–	–	250	μA	–
SID219	I _{IMO2}	IMO operating current at 24 MHz	–	–	180	μA	–

Table 31. IMO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	F _{IMOTOL1}	Frequency variation at 24, 32, and 48 MHz (trimmed)	–	–	±2	%	
SID226	T _{STARTIMO}	IMO startup time	–	–	7	μs	–
SID228	T _{JITRMSIMO2}	RMS jitter at 24 MHz	–	145	–	ps	–

Internal Low-Speed Oscillator

Table 32. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231 ^[12]	I _{ILO1}	ILO operating current	–	0.3	1.05	μA	–

Table 33. ILO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234 ^[12]	T _{STARTILO1}	ILO startup time	–	–	2	ms	–
SID236 ^[12]	T _{ILODUTY}	ILO duty cycle	40	50	60	%	–
SID237	F _{ILOTRIM1}	ILO frequency range	20	40	80	kHz	–

Note

12. Guaranteed by characterization.

Table 34. Watch Crystal Oscillator (WCO) Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID398	FWCO	Crystal Frequency	–	32.768	–	kHz	
SID399	FTOL	Frequency tolerance	–	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	–	50	–	kΩ	
SID401	PD	Drive Level	–	–	1	μW	
SID402	TSTART	Startup time	–	–	500	ms	
SID403	CL	Crystal Load Capacitance	6	–	12.5	pF	
SID404	C0	Crystal Shunt Capacitance	–	1.35	–	pF	
SID405	IWCO1	Operating Current (high power mode)	–	–	8	uA	
SID406	IWCO2	Operating Current (low power mode)	–	–	1	uA	

Table 35. External Clock Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305 ^[13]	ExtClkFreq	External clock input frequency	0	–	48	MHz	–
SID306 ^[13]	ExtClkDuty	Duty cycle; measured at V _{DD/2}	45	–	55	%	–

Table 36. Block Specs

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID262 ^[13]	T _{CLKSWITCH}	System clock source switching time	3	–	4	Periods	–

Table 37. Smart I/O Pass-through Time (Delay in Bypass Mode)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID252	PRG_BYPASS	Max delay added by Smart I/O in bypass mode	–	–	1.6	ns	

Note

13. Guaranteed by characterization.

Packaging

The PSoC 4100S will be offered in 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball WLCSP packages. Package dimensions and Cypress drawing numbers are in the following table.

Table 38. Package List

Spec ID#	Package	Description	Package Dwg
BID20	48-pin TQFP	7 × 7 × 1.4-mm height with 0.5-mm pitch	51-85135
BID20A	44-pin TQFP	10 × 10 × 1.6-mm height with 0.8-mm pitch	51-85064
BID27	40-pin QFN	6 × 6 × 0.6-mm height with 0.5-mm pitch	001-80659
BID34A	32-pin QFN	5 × 5 × 0.6-mm height with 0.5-mm pitch	001-42168
BID34D	35-ball WLCSP	2.6 × 2.1 × 0.48-mm height with 0.35-mm pitch	002-09958

Table 39. Package Thermal Characteristics

Parameter	Description	Package	Min	Typ	Max	Units
T _A	Operating Ambient temperature		−40	25	85	°C
T _J	Operating junction temperature		−40	—	100	°C
T _{JA}	Package θ _{JA}	48-pin TQFP	—	74.8	—	°C/Watt
T _{JC}	Package θ _{JC}	48-pin TQFP	—	35.7	—	°C/Watt
T _{JA}	Package θ _{JA}	44-pin TQFP	—	57.2	—	°C/Watt
T _{JC}	Package θ _{JC}	44-pin TQFP	—	17.5	—	°C/Watt
T _{JA}	Package θ _{JA}	40-pin QFN	—	17.8	—	°C/Watt
T _{JC}	Package θ _{JC}	40-pin QFN	—	2.8	—	°C/Watt
T _{JA}	Package θ _{JA}	32-pin QFN	—	19.9	—	°C/Watt
T _{JC}	Package θ _{JC}	32-pin QFN	—	4.3	—	°C/Watt
T _{JA}	Package θ _{JA}	35-ball WLCSP	—	43	—	°C/Watt
T _{JC}	Package θ _{JC}	35-ball WLCSP	—	0.3	—	°C/Watt

Table 40. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 41. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

Package	MSL
All except WLCSP	MSL 3
35-ball WLCSP	MSL 1

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